L Number	Hits	Search Text	DB	Time stamp
1	1	@ad<=20020109 and 'copper wiring bond pad' same 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 11:00
2	0	@ad<=20020109 and 'copper wiring' same 'alumimun' same 'bond pad' same 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 10:54
3	0	@ad<=20020109 and 'copper wire' same 'alumimun' same 'bond pad' same 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 10:54
4	0	@ad<=20020109 and 'copper wire' same 'alumimun' same 'bond pad' same 'intermetal dielectric layer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 11:07
5	6	@ad<=20020109 and 'bond pad' same 'intermetal dielectric layer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 10:55
6	22	@ad<=20020109 and 'wiring bond pad'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 11:06
7	0	@ad<=20020109 and 'under pad' and 'copper' with 'buffer' and 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 11:06
8	0	@ad<=20020109 and 'copper' with 'Al buffer' and 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 11:07
9	772	@ad<=20020109 and 'intermetal dielectric layer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 11:08
10	14	@ad<=20020109 and 'intermetal dielectric layer' and 'bond pads'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 11:27
11	2	@ad<=20020109 and 'intermetal dielectric layer' and 'copper' adj1 'connection pads'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 11:19
12	13	@ad<=20020109 and 'reinforce' with 'bond pads'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 11:27
-	2054	(438/612).ccls. or (438/597).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/30 10:09
-	337	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and copper and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:04

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-	74	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and 'bonding pad' with 'integrated circuit'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 10:01
-	1	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and Cu adj bonding adj pad with 'integrated circuit'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:13
-	6	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and Copper adj bonding adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:14
-	1143	@ad<=20020109 and cu adj 'bonding pad' with 'IMD' or 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:10
-	0	@ad<=20020109 and cu adj 'bonding pad' with 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/14 10:46
-	0	@ad<=20020109 and cu adj 'bonding pad' with 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:00
-	6	@ad<=20020109 and cu adj 'bonding pad' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 09:03
-	3	@ad<=20020109 and cu adj 'bonding pad' and 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:43
-	1	"3942245".PN.	USPAT	2002/08/21 11:40
-	1	"5075965".PN.	USPAT	2002/08/21 11:40
-	1	"5288006".PN.	USPAT	2002/08/21 11:40
-	1	"5376235".PN.	USPAT	2002/08/21 11:41
-	1	"5384284".PN.	USPAT	2002/08/21 11:41
-	1	"5436412".PN.	USPAT	2002/08/21 11:42
-	0	@ad<=20020109 and copper adj bonding adj pad with 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 09:52
-	4	@ad<=20020109 and copper adj bonding adj pad and 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:46
-	809	(228/180.21).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:48
-	93	((228/180.21).CCLS.) and bonding adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 11:50

-	9	((228/180.21).CCLS.) and bonding adj pad with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:32
-	8	((228/180.21).CCLS.) and bond adj pad with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:30
-	0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al' adj buffer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:45
-	0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:31
-	639	@ad<=20010119 and bonding adj pad with copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:36
-	359	@ad<=20010119 and bonding adj pad with copper and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:47
-	30	@ad<=20010119 and copper adj bonding adj pad and aluminum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 13:59
-	839	@ad<=20010119 and bonding adj pad and aluminum and buffer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 14:00
-	4120	'bonding pad' and apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:03
-	3573	((257/459) or (257/676) or (257/786) or (275/670) or (257/672)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:07
-	1779	(438/612).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:47
-	1	bond adj pad with copper with 'Al' and 'buffer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:46
-	11	'bond' and 'pad' with copper with 'Al' and 'buffer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:54
-	284	(438/48).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:47

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-	1722	(438/614).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:35
-	573	(257/459).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:35
-	1222	(257/784).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:37
-	1209	(257/786).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:39
-	735	(257/781-782).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:40
-	1392	(257/774).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 11:44
-	1	'bond pad' with 'copper' with 'Al' and 'buffer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:55
-	1	'bonding pad' with 'copper' with 'Al' and 'buffer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 08:56
-	122	'bonding pad' with 'Cu' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 09:05
-	117	@ad<=20020109 and 'bonding pad' with 'Cu' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 09:01
-	6	@ad<=20020109 and cu adj 'bonding pad' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 09:03
-	117	@ad<=20020109 and 'bonding pad' with 'Cu' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 11:18
-	1	"4811081".PN.	USPAT	2003/01/23 09:57
-	1	"5001542".PN.	USPAT	2003/01/23 09:57
-	1	"6108212".PN.	USPAT	2003/01/23 09:57
-	1	"6064120".PN.	USPAT	2003/01/23 09:58

-	246	@ad<=20020109 and 'bonding pad' with 'integrated circuit' and 'Cu' and 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 10:02
-	231	(257/784).ccls. and @ad<=20020109 and 'Copper' and 'aluminum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 10:38
-	2356	(438/612).ccls. or (438/597).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:34
-	798	(228/180.21).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:35
-	2531	(438/613-617).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:38
-	586	(257/459).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:39
-	1320	(257/784).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:40
-	1288	(257/786).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:42
-	782	(257/781-782).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:44
-	1782	(257/676).ccls. and @ad<=20020109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 10:46
-	27	@ad<=20020109 and 'bonding pad' near3 'Cu' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 11:19
-	63	@ad<=20020109 and 'bonding pad' near3 'Copper' with 'Aluminum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 11:32
-	34	@ad<=20020109 and CVC.as. and interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/05 11:34
-	1	("6333559").PN.	USPAT	2003/08/05 11:38
-	4	(("5785236") or ("6197613") or ("6162652") or ("6555759")).PN.	USPAT	2003/08/05 11:40
-	0	"20020164840"	USPAT	2003/08/05 11:41

-	0	"2002/0164840"	USPAT	2003/08/05 11:42
-	2	"20020164840"	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/05 11:42
-	2	"20010035452"	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/05 11:43
-	2	"20020047218"	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/05 11:43
-	4	"2003012776"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 11:23
-	2	"20030127716"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 11:23
-	0	@ad<=20020109 and 'wiring bonding pad' and 'intermetal dielectric' and 'metal layer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:04
-	0	@ad<=20020109 and 'wiring bonding pad' and 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:04
-	209	@ad<=20020109 and 'wiring bonding pad'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:10
-	22	@ad<=20020109 and 'wiring bond pad'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:04
-	44	@ad<=20020109 and 'copper' and 'bonding pad' and 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:48
-	40	@ad<=20020109 and 'copper' and 'bond pads' and 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:48
-	69	@ad<=20020109 and 'bond pads' and 'IMD'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:54
-	107	@ad<=20020109 and 'bond pads' same 'mechanical stress'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:59
-	108	@ad<=20020109 and 'bonding pad' same 'mechanical stress'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/22 12:59

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-	1	@ad<=20020109 and 'bond pads' same 'buffer layer' same 'bonding layer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 09:54
-	1	@ad<=20020109 and 'bonding pad' same 'buffer' same 'bonding layer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 09:57
-	13	@ad<=20020109 and 'UBM' and 'bond pads' and 'buffer' and 'bonding'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 10:00
-	497	@ad<=20020109 and 'bond pads' and 'EDS'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 10:12
-	2	@ad<=20020109 and 'bond pads' with 'EDS'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 10:03
-	315	chou.in. and taiwan	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 10:06
-	0	chou-kuo.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 10:04
-	25	kuo-yu.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 10:06
-	1	@ad<=20020109 and 'single layer' near 'wiring bond pad'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 10:13
-	22	@ad<=20020109 and 'wiring bond pad'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/23 10:13
-	2	("6378759").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/30 10:09

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